

## Features

- AEC-Q101 Qualified
- Split Gate Trench MOSFET Technology
- Excellent Package for Heat Dissipation
- High Density Cell Design for Low R<sub>DS(ON)</sub>
- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

### **Maximum Ratings**

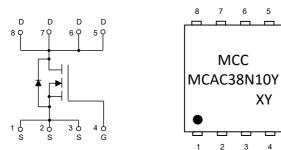
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 20°C/W Junction to Ambient(t≤10s)<sup>(2)</sup>
- Thermal Resistance: 50°C/W Junction to Ambient(Steady-State)<sup>(2)</sup>
- Thermal Resistance: 1.8°C/W Junction to Case(Steady-State)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V <sub>DS</sub>	100	V
Gate-Source Volltage	V <sub>GS</sub>	±20	V
Continuous Drain Current	I <sub>D</sub>	38	Α
Pulsed Drain Current <sup>(3)</sup>	I <sub>DM</sub>	120	Α
Total Power Dissipation <sup>(4)</sup>	P <sub>D</sub>	70	W
Single Pulsed Avalanche Energy <sup>(5)</sup>	E <sub>AS</sub>	81	mJ

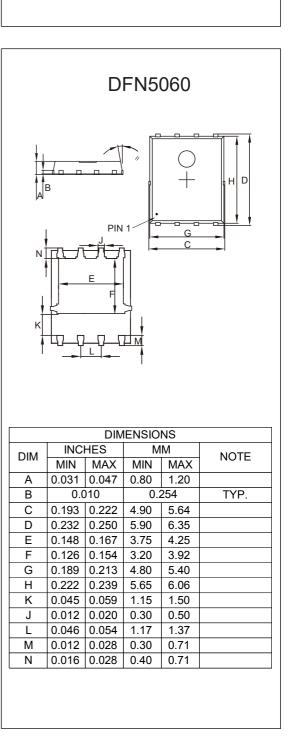
Note:

- 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 2. The value of R<sub>0JA</sub> is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub> =25°C. The Power dissipation P<sub>DSM</sub> is based on R<sub>0JA</sub> t ≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
- 3. Repetitive rating; pulse width limited by max. junction temperature.
- 4.  $\mathsf{P}_\mathsf{D}$  is based on max. junction temperature, using junction-case thermal resistance.
- 5.  $T_J$ =25°C,  $V_{DD}$ =50V,  $R_G$ =25 $\Omega$ , L=0.5mH.

## Internal Structure and Marking Code



2 codes in total X is the year Y is the month



**N-CHANNEL** 

MOSFET



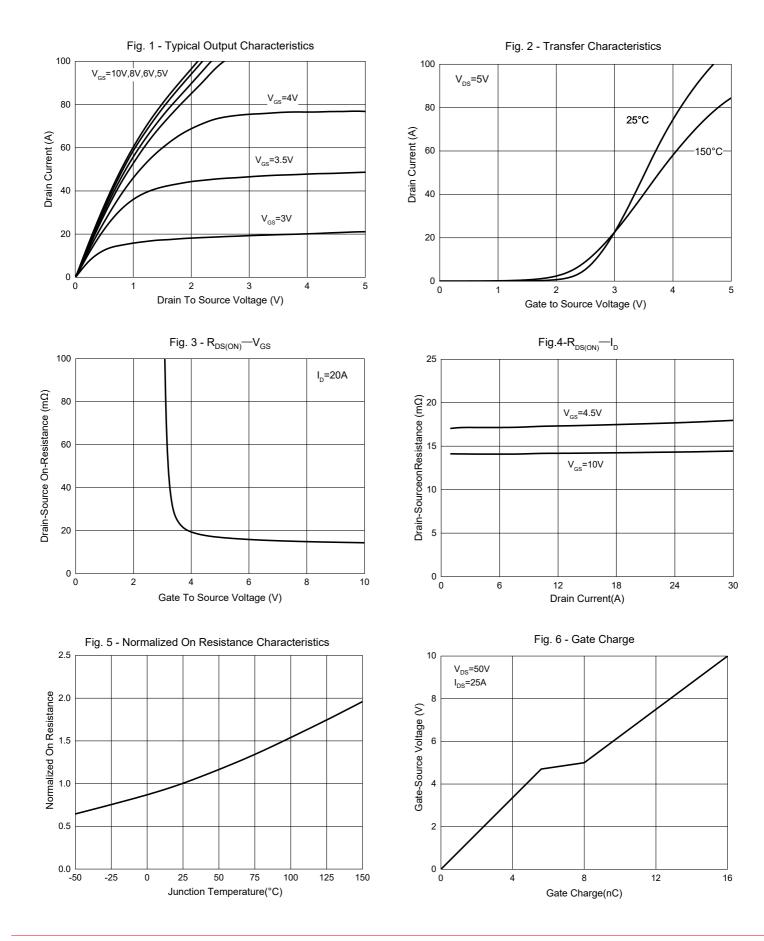
## Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static Characteristics				I	I	I	
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250µA	100			V	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V			1	μA	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	1	1.8	2.5	V	
Drain-Source On-Resistance		V <sub>GS</sub> =10V, I <sub>D</sub> =20A		15	19	mΩ	
	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A		18	23	mΩ	
Gate Resistance	R <sub>g</sub>	F=1 MHz, Open drain		1.4		Ω	
Diode Characteristics							
Continuous Body Diode Current	Is				38	А	
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =20A			1.3	V	
Reverse Recovery Time	t <sub>rr</sub>			39.8		ns	
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =20A, dI <sub>F</sub> /dt=100A/μs		42		nC	
Dynamic Characteristics			·				
Input Capacitance	C <sub>iss</sub>			1150			
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =50V,V <sub>GS</sub> =0V,f=1MHz		370		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			8			
Total Gate Charge	Qg			16			
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =50V,V <sub>GS</sub> =10V,I <sub>D</sub> =25A		5.6		nC	
Gate-Drain Charge	Q <sub>gd</sub>			2.4			
Turn-On Delay Time	t <sub>d(on)</sub>			39.2			
Turn-On Rise Time	t <sub>r</sub>	V <sub>DD</sub> =50V, V <sub>GS</sub> =10V,		11			
Turn-Off Delay Time	t <sub>d(off)</sub>	R <sub>GEN</sub> =2.2Ω, I <sub>DS</sub> =25A		53.2		ns	
Turn-Off Fall Time	t <sub>f</sub>			15.8			

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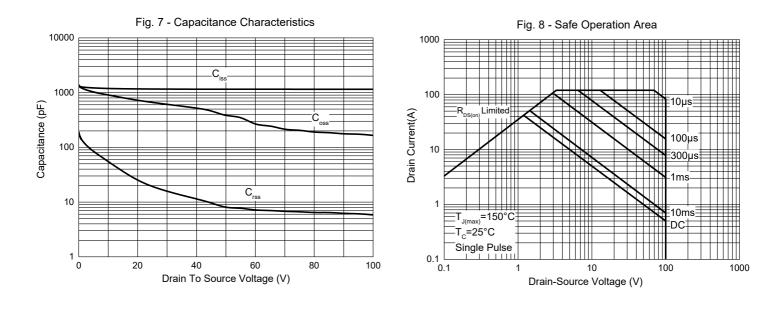


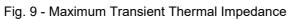
# **Curve Characteristics**

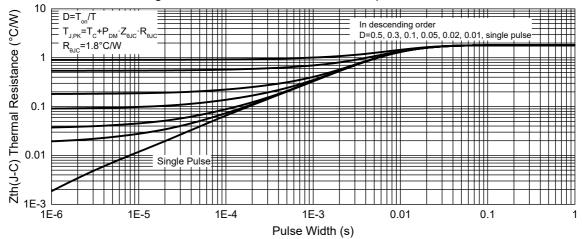




# **Curve Characteristics**









## **Ordering Information**

Device	Packing	
Part Number-TP	Tape&Reel: 5Kpcs/Reel	

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